

Electronic Patent Application Fee Transmittal

Application Number:	10520444			
Filing Date:	06-Jan-2005			
Title of Invention:	Hygroscopic molding			
First Named Inventor/Applicant Name:	Teruo Uchibori			
Filer:	Raymond D. Smith/MARY NGUYEN			
Attorney Docket Number:	SAEG103.003APC			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				490